

## **Application Data Sheet**

### **Application Information**

Application Type::	Regular
Subject Matter::	Utility
CD-ROM or CD-R?::	None
Title::	Method and Apparatus for Thixotropic Molding of Semisolid Alloys
Attorney Docket Number::	wjliu-005
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	9
Small Entity::	Yes
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

### **Applicant Information**

Applicant Authority type::	Inventor
Primary Citizenship Country:	Canada
Status::	Full Capacity
Given Name::	Wayne (Weijie) J.
Family Name::	Liu
City of Residence::	Toronto
State of Province of Residence::	ON
Country of Residence::	Canada
Street of mailing address::	103-2181 Navaho Dr.
City of mailing address::	Ottawa
State or Province of mailing address::	ON
Postal or Zip Code of mailing address::	K2C 3K3

**Correspondence Information**

Name:: Wayne J. Liu  
Street of mailing address:: 103-2181 Navaho Dr.  
City of mailing address:: Ottawa  
State or Province of mailing address:: ON  
Country of mailing address:: Canada  
Postal or Zip Code of mailing address:: K2C 3K3

Phone Number:: (613) 727-5995  
E-Mail address:: waynejliu@hotmail.com

**Domestic Priority Information**

Application::	Continuity Type:	Parent Application::	Parent Filing Date::
This Application	An application claiming the benefit under 35 USC 119(e)	60/442,481	01/27/03